

# ADHESIVE COMPOSITIONS CONTAINING ORGANIC SPACERS AND METHODS FOR USE THEREOF

## ABSTRACT

In accordance with the present invention, there are provided adhesive compositions and methods for use thereof, comprising at least one maleimide-containing monomer, at least one cure initiator, and a plurality of spacer elements constructed from one or more organic polymers. Invention adhesive compositions are useful for controlling bond line thickness and planarity between a device and a substrate. Bond line thickness and planarity is largely determined by the size of the spacer elements in the adhesive composition.

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